

fastPACK 0 H 2nd gen

V23990-P729-F46-01-14

| Maximum Ratings / Höchstzulässige Werte | | P729-F46 1200V/25A | | |
|---|-----------|--------------------|--------------------------|------|
| Parameter | Condition | Symbol | Datasheet values max. | Unit |

DC link Capacitor
DC link Kondensator

| | | | | |
|---------------------------------------|----------------------|------------------|------|---|
| Max.DC voltage Max. Gleichspannung | T _C =25°C | U _{MAX} | 1000 | V |
|---------------------------------------|----------------------|------------------|------|---|

Transistor H-bridge(IGBT)
Transistor H-Brücke(IGBT)

| | | | | |
|---|---|--------------------|------|----|
| Collector-emitter break down voltage Kollektor-Emitter-Sperrspannung | | V _{CE} | 1200 | V |
| DC collector current Kollektor-Dauergleichstrom | T _j =T _{jmax} Th=80°C, T _c =80°C | I _C | 30 | A |
| Repetitive peak collector current Periodischer Kollektorspitzenstrom | tp limited by T _j max | I _{cpuls} | 75 | A |
| Power dissipation per IGBT Verlustleistung pro IGBT | T _j =T _{jmax} Th=80°C T _c =80°C | P _{tot} | 73 | W |
| Gate-emitter peak voltage Gate-Emitter-Spitzenspannung | | V _{GE} | ±20 | V |
| SC withstand time* Kurzschlußverhalten* | T _j =T _{jmax} V _{GE} =15V V _{CC} =360V | t _{SC} | 10 | us |
| max. Chip temperature max. Chiptemperatur | | T _{jmax} | 150 | °C |

Diode H-bridge
Diode H-Brücke

| | | | | |
|--|--|-------------------|-----|----|
| DC forward current Dauergleichstrom | T _j =T _{jmax} Th=80°C, T _c =80°C | I _F | 18 | A |
| Repetitive peak forward current Periodischer Spitzenstrom | tp limited by T _j max | I _{FRM} | 50 | A |
| Power dissipation per Diode Verlustleistung pro Diode | T _j =T _{jmax} Th=80°C T _c =80°C | P _{tot} | 35 | W |
| max. Chip temperature max. Chiptemperatur | | T _{jmax} | 150 | °C |

Thermal properties
Thermische Eigenschaften

| | | | | |
|---|--|------------------|------------|----|
| Storage temperature Lagertemperatur | | T _{stg} | -40...+125 | °C |
| Operation temperature Betriebstemperatur | | T _{op} | -40...+125 | °C |

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Maximum Ratings / Höchstzulässige Werte
P729-F46 1200V/25A

| Parameter | Condition | Symbol | Datasheet values max. | Unit |
|-----------|-----------|--------|--------------------------|------|
|-----------|-----------|--------|--------------------------|------|

Insulation properties
Modulisation

| | | | | |
|--|--------|----------|----------|-----|
| Insulation voltage Isolationsspannung | t=1min | V_{is} | 4000 | Vdc |
| Creepage distance Kriechstrecke | | | min 12,7 | mm |
| Clearance Luftstrecke | | | min 12,7 | mm |

Additional notes and remarks:

** Allowed number of short circuits must be less than 1000 times, and time duration between short circuits should be more than 1 second!*

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| Characteristic values/ Charakteristische Werte | | P729-F46 | | | | | | | | | |
|--|-----------------------|---|---|------------------|------------------|----------------------|------------------|--------------|------|------|------|
| Description | Symbol | Conditions | | | | | Datasheet values | | | Unit | |
| | | T(C°) | Other conditions (Rgon-Rgoff) | VGE(V) VGS(V) | VCE(V) VDS(V) | IC(A) IF(A) Id(A) | Min | Typ | Max | | |
| Capacitor | | | | | | | | | | | |
| Kondensator | | | | | | | | | | | |
| C value | C | | | | | | 45 | 56 | 67 | nF | |
| C Wert | | | | | | | | | | | |
| Transistor H-bridge(IGBT) | | | | | | | | | | | |
| Transistor H-Brücke(IGBT) | | | | | | | | | | | |
| Gate emitter threshold voltage Gate-Schwelligenspannung | V _{GE(th)} | T _J =25°C T _J =125°C | VCE=VGE | | | 1m | 4 | 5,5 | 7 | V | |
| Collector-emitter saturation voltage Kollektor-Emitter Sättigungsspannung | V _{CE(sat)} | T _J =25°C T _J =125°C | | 15 | | 25 | | 2,12 2,24 | 2,9 | V | |
| Collector-emitter cut-off Kollektor-Emitter Reststrom | I _{CES} | T _J =25°C T _J =125°C | | 0 | 600 | | | | 0,1 | mA | |
| Gate-emitter leakage current Gate-Emitter Reststrom | I _{GES} | T _J =25°C T _J =125°C | | 20 | 0 | | | | 200 | nA | |
| Integrated Gate resistor Integrierter Gate Widerstand | R _{gint} | | | | | | | none | | Ω | |
| Turn-on delay time Einschaltverzögerungszeit | t _{td(on)} | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 131 | ns | |
| Rise time Anstiegszeit | t _r | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 15 | ns | |
| Turn-off delay time Abschaltverzögerungszeit | t _{td(off)} | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 233 | ns | |
| Fall time Fallzeit | t _f | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 92 | ns | |
| Turn-on energy loss per pulse Einschaltverlustenergie pro Puls | E _{on} | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 1,35 | mWs | |
| Turn-off energy loss per pulse Abschaltverlustenergie pro Puls | E _{off} | T _J =25°C T _J =125°C | Rgoff=16 Ω Rgon=16 Ω | | ±15 | 600 | 25 | | 1,76 | mWs | |
| Input capacitance Eingangskapazität | C _{ies} | T _J =25°C T _J =125°C | f=1MHz | 0 | 25 | | | | 2,02 | nF | |
| Output capacitance Ausgangskapazität | C _{oss} | T _J =25°C T _J =125°C | f=1MHz | 0 | 25 | | | | 0,19 | nF | |
| Reverse transfer capacitance Rückwirkungskapazität | C _{ies} | T _J =25°C T _J =125°C | f=1MHz | 0 | 25 | | | | 0,06 | nF | |
| Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip | R _{th,jh} | | Thermal grease thickness:50um Wärmeleitpaste Dicke:50um λ = 0.61 W/mK | | | | | | 0,95 | K/W | |
| Diode H-bridge | | | | | | | | | | | |
| Diode H-Brücke | | | | | | | | | | | |
| Diode forward voltage Durchlaßspannung | V _F | T _J =25°C T _J =125°C | | | | 25 | 1 | 2,65 2,31 | 4 | V | |
| Peak reverse recovery current Rückstromspitze | I _{RM} | T _J =25°C T _J =125°C | Rgon=16 Ω | | ±15 | 600 | 25 | | 54,5 | A | |
| Reverse recovery time Sperrverzögerungszeit | t _{rr} | T _J =25°C T _J =125°C | Rgon=16 Ω | | ±15 | 600 | 25 | | 147 | ns | |
| Reverse recovered charge Sperrverzögerungsladung | Q _{rr} | T _J =25°C T _J =125°C | Rgon=16 Ω | | ±15 | 600 | 25 | | 3,42 | uC | |
| Reverse recovered energy Sperrverzögerungsenergie | E _{rec} | T _J =25°C T _J =125°C | Rgon=16 Ω | | ±15 | 600 | 25 | | 1,55 | mWs | |
| Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip | R _{th,jh} | | Thermal grease thickness | | | | | | 1,99 | K/W | |
| Thermal resistance chip to case per chip Wärmewiderstand Chip-Gehäuse pro Chip | R _{th,jc} | | Wärmeleitpaste Dicke:50u | | | | | | | K/W | |
| NTC-Thermistor | | | | | | | | | | | |
| NTC-Widerstand | | | | | | | | | | | |
| Rated resistance Nennwiderstand | R ₂₅ | T _J =25°C | Tol. ±5% | | | | | 20,9 | 22 | 23,1 | kOhm |
| Deviation of R100 Abweichung von R100 | D _{R/R} | T _C =100°C | R100=1503Ω | | | | | | 2,9 | | %/K |
| Power dissipation given Epcos-Typ Verlustleistung Epcos-Typ angeben | P | T _J =25°C | | | | | | | 210 | | mW |
| B-value B-Wert | B _(25/100) | T _J =25°C | Tol. ±3% | | | | | | 3980 | | K |

Output inverter

Figure 1. Typical output characteristics
 Output inverter IGBT
 $I_c = f(V_{CE})$

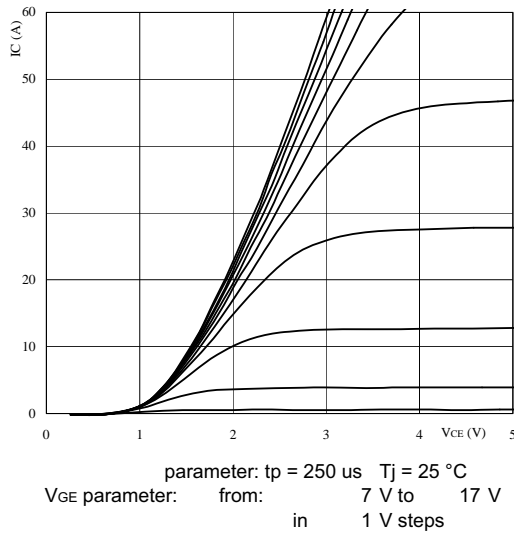


Figure 2. Typical output characteristics
 Output inverter IGBT
 $I_c = f(V_{CE})$

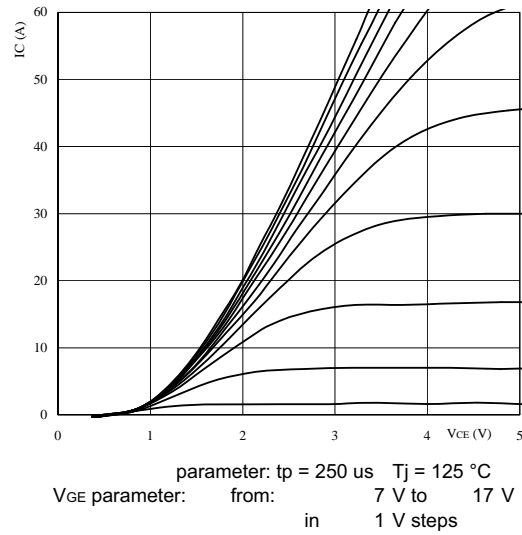


Figure 3. Typical transfer characteristics
 Output inverter IGBT
 $I_c = f(V_{GE})$

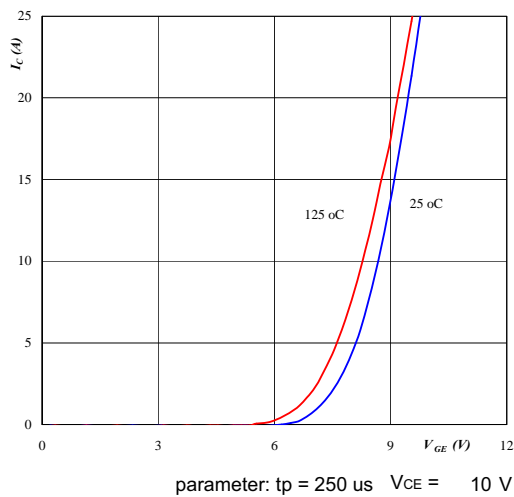
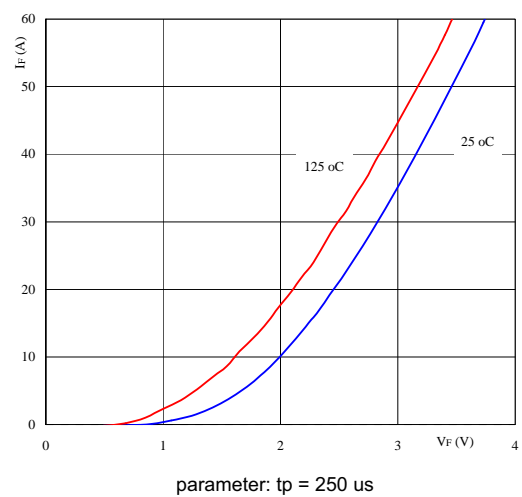
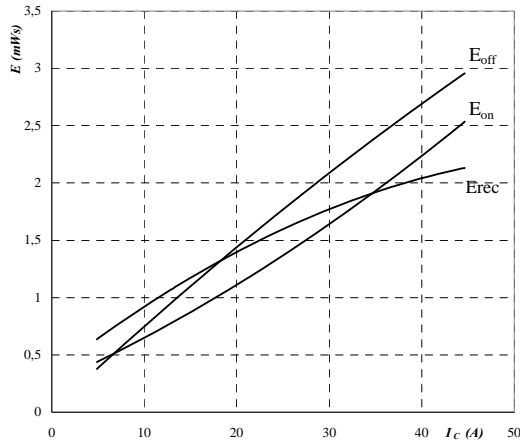


Figure 4. Typical diode forward current as a function of forward voltage
 Output inverter FRED $I_F = f(V_F)$



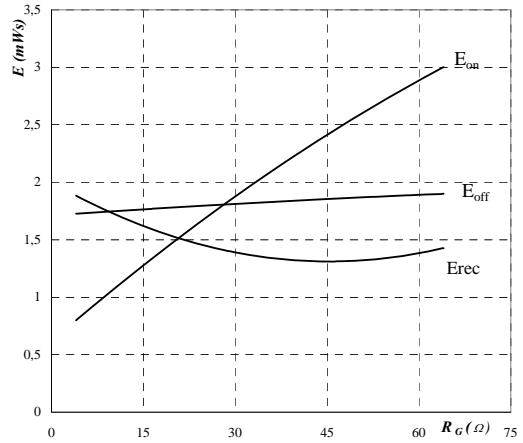
Output inverter

Figure 5. Typical switching energy losses as a function of collector current
 Output inverter IGBT
 $E = f(I_c)$



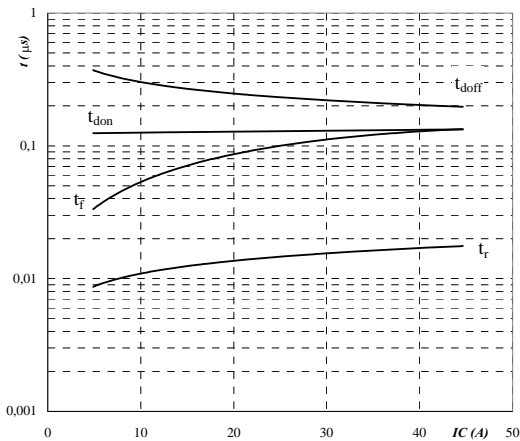
inductive load, $T_j = 125\text{ }^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $R_{gon} = 16\ \Omega$
 $R_{goff} = 16\ \Omega$

Figure 6. Typical switching energy losses as a function of gate resistor
 Output inverter IGBT
 $E = f(R_G)$



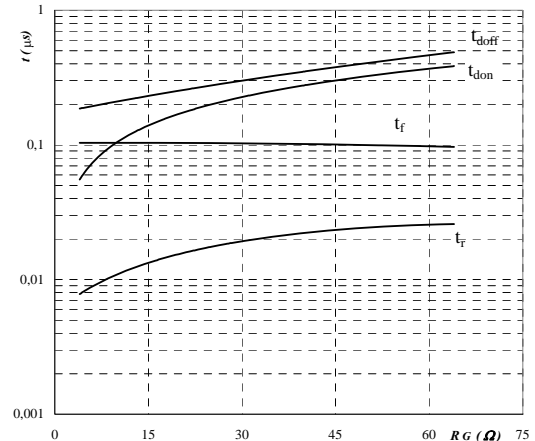
inductive load, $T_j = 125\text{ }^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $I_c = 25\text{ A}$

Figure 7. Typical switching times as a function of collector current
 Output inverter IGBT
 $t = f(I_c)$



inductive load, $T_j = 125\text{ }^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $R_{gon} = 16\ \Omega$
 $R_{goff} = 16\ \Omega$

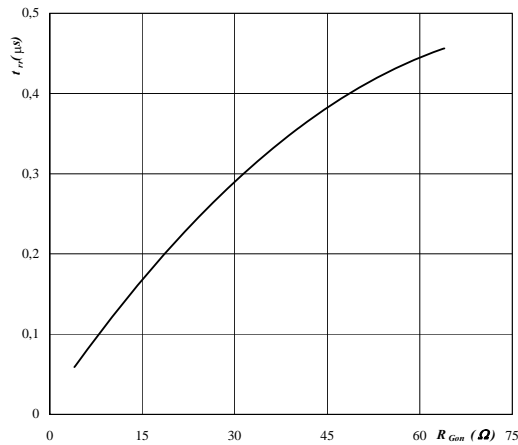
Figure 8. Typical switching times as a function of gate resistor
 Output inverter IGBT
 $t = f(R_G)$



inductive load, $T_j = 125\text{ }^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $I_c = 25\text{ A}$

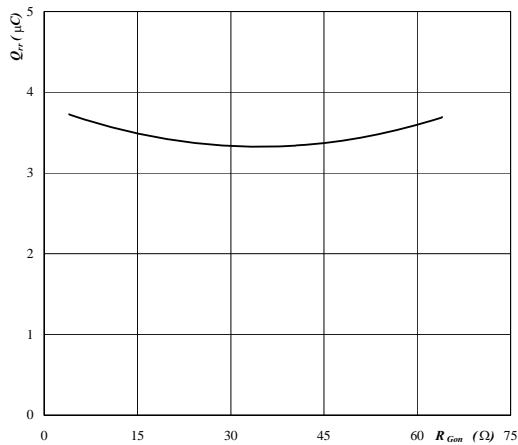
Output inverter

Figure 9. Typical reverse recovery time as a function of IGBT turn on gate resistor
 Output inverter FRED diode
 $t_{rr} = f(R_{gon})$



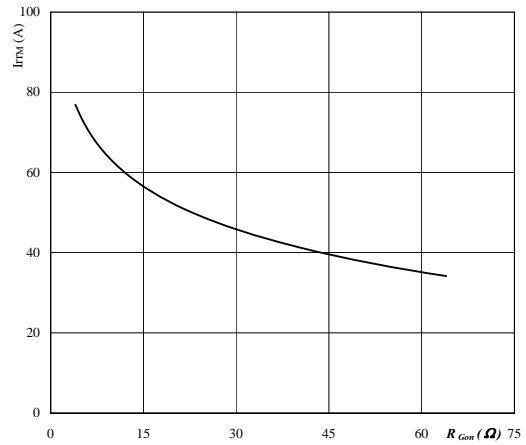
$T_j = 125\text{ }^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 25\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

Figure 11. Typical reverse recovery charge as a function of IGBT turn on gate resistor
 Output inverter FRED diode
 $Q_{rr} = f(R_{gon})$



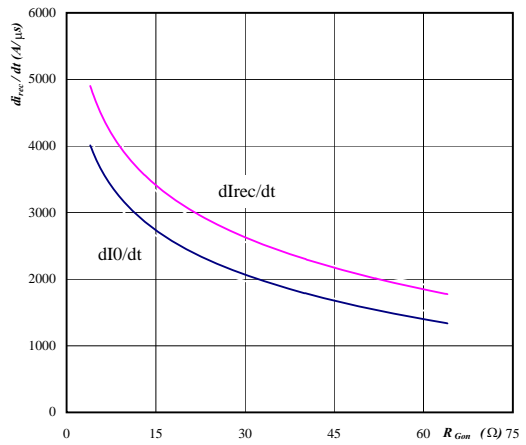
$T_j = 125\text{ }^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 25\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

Figure 10. Typical reverse recovery current as a function of IGBT turn on gate resistor
 Output inverter FRED diode
 $I_{RRM} = f(R_{gon})$



$T_j = 125\text{ }^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 25\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

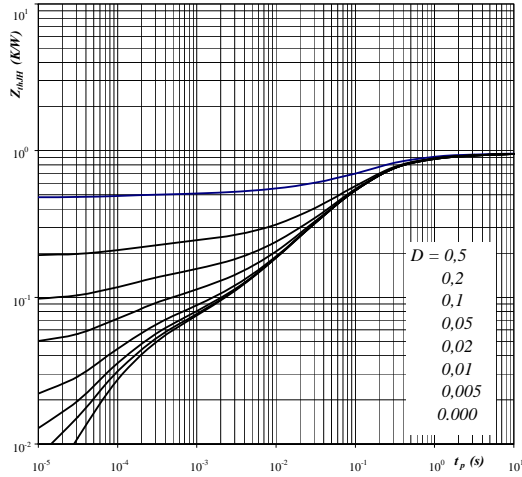
Figure 12. Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor
 Output inverter FRED diode
 $dI_O/dt, dI_{rec}/dt = f(R_{gon})$



$T_j = 125\text{ }^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 25\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

Output inverter

Figure 13. IGBT transient thermal impedance as a function of pulse width
 $Z_{thJH} = f(t_p)$

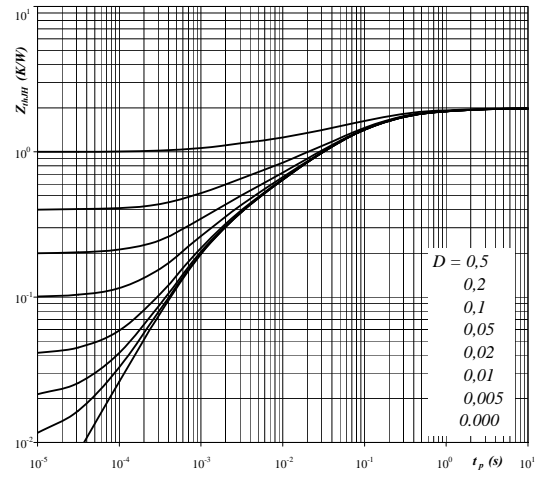


Parameter: $D = t_p / T$ $R_{thJH} = 0,95 \text{ K/W}$

IGBT thermal model values

| R (C/W) | Tau (s) |
|---------|---------|
| 0,02 | 1,6E+01 |
| 0,10 | 1,7E+00 |
| 0,30 | 2,6E-01 |
| 0,36 | 8,0E-02 |
| 0,11 | 1,1E-02 |
| 0,03 | 8,0E-04 |

Figure 14. FRED transient thermal impedance as a function of pulse width
 $Z_{thJH} = f(t_p)$



Parameter: $D = t_p / T$ $R_{thJH} = 1,99 \text{ K/W}$

FRED thermal model values

| R (C/W) | Tau (s) |
|---------|---------|
| 0,03 | 1,1E+01 |
| 0,17 | 1,1E+00 |
| 0,65 | 1,6E-01 |
| 0,60 | 3,9E-02 |
| 0,32 | 7,4E-03 |
| 0,23 | 1,1E-03 |

Output inverter

Figure 15. Power dissipation as a function of heatsink temperature
Output inverter IGBT
 $P_{tot} = f(T_h)$

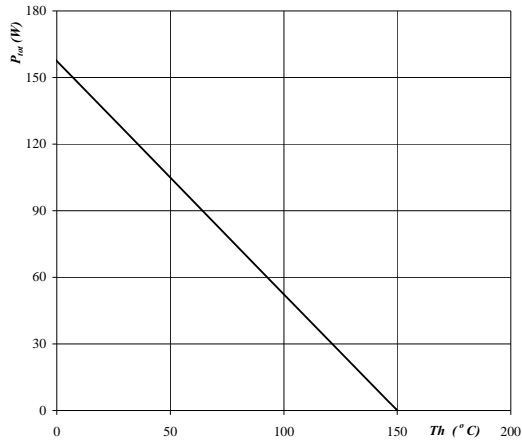

parameter: T_j = 150 °C

Figure 16. Collector current as a function of heatsink temperature
Output inverter IGBT
 $I_c = f(T_h)$

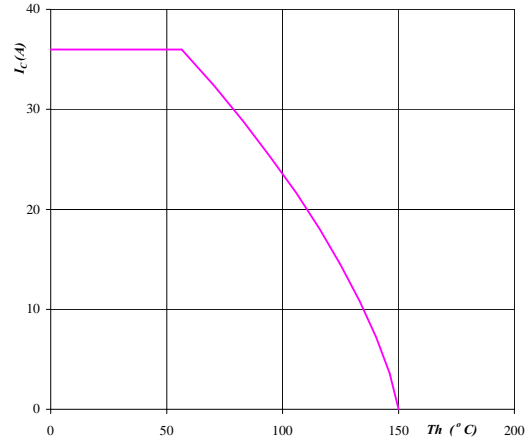

parameter: T_j = 150 °C
V_{GE} = 15 V

Figure 17. Power dissipation as a function of heatsink temperature
Output inverter FRED
 $P_{tot} = f(T_h)$

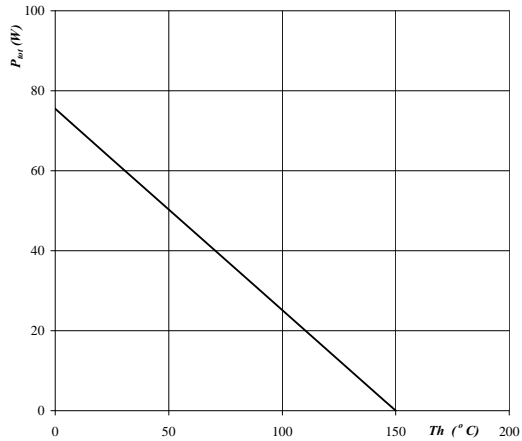
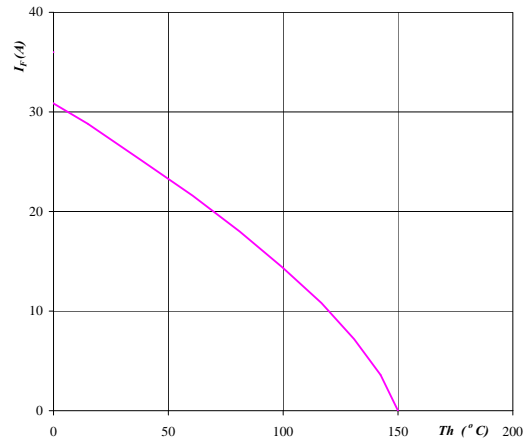

parameter: T_j = 150 °C

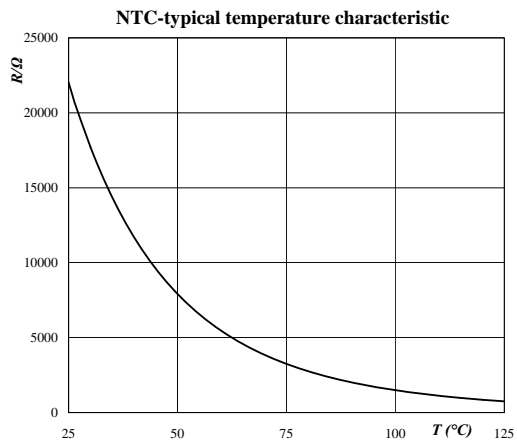
Figure 18. Forward current as a function of heatsink temperature
Output inverter FRED
 $I_F = f(T_h)$


parameter: T_j = 150 °C

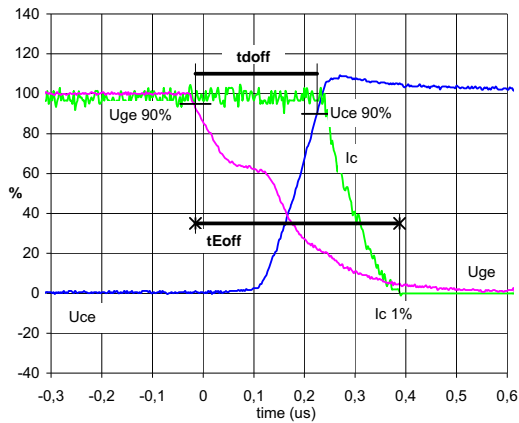
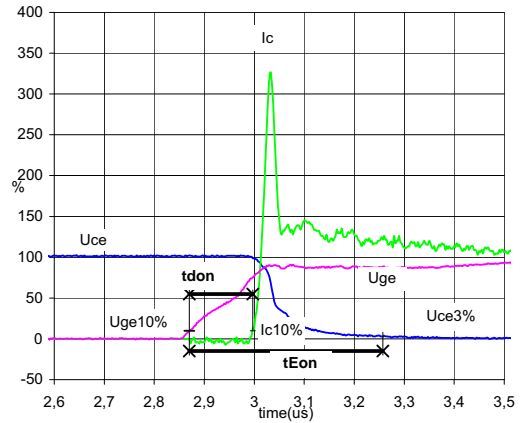
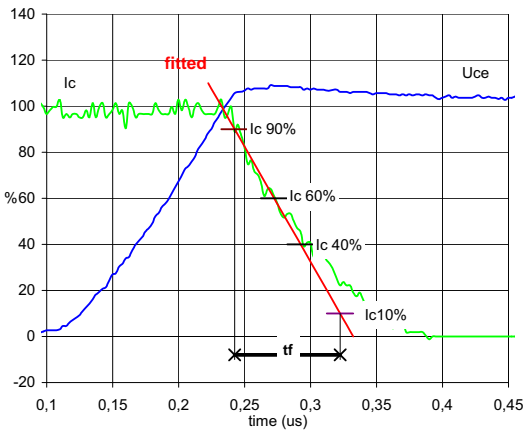
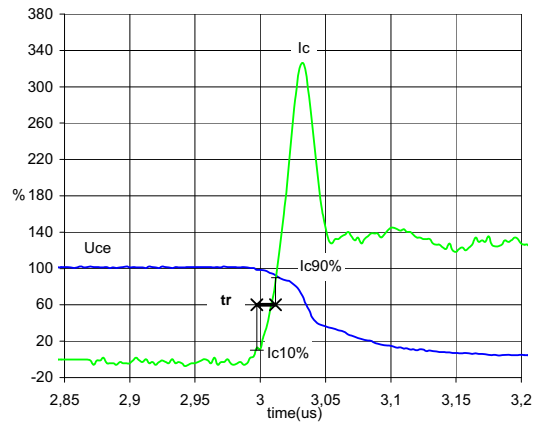
Thermistor

Figure 19. Typical NTC characteristic as a function of temperature

$$R_T = f(T)$$

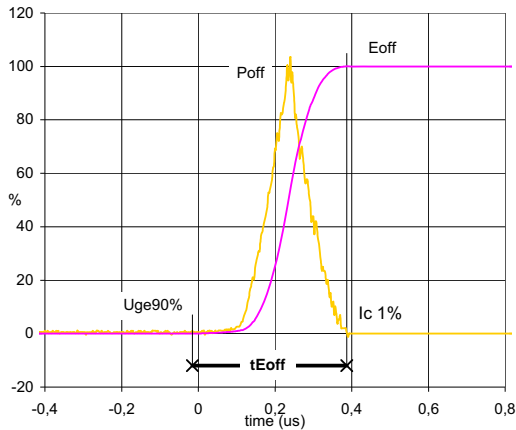


Switching definitions

 General conditions: $T_J = 125\text{ }^\circ\text{C}$
 $R_{gon} = 16\ \Omega$ $R_{goff} = 16\ \Omega$
Figure 1. Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 (t_{Eoff} = integrating time for E_{off})
 Output inverter IGBT

 $U_{ge}(0\%) = -15\text{ V}$
 $U_{ge}(100\%) = 15\text{ V}$
 $U_c(100\%) = 600\text{ V}$
 $I_c(100\%) = 25\text{ A}$
 $t_{doff} = 0,23\ \mu\text{s}$
 $t_{Eoff} = 0,40\ \mu\text{s}$
Figure 2. Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
 (t_{Eon} = integrating time for E_{on})
 Output inverter IGBT

 $U_{ge}(0\%) = -15\text{ V}$
 $U_{ge}(100\%) = 15\text{ V}$
 $U_c(100\%) = 600\text{ V}$
 $I_c(100\%) = 25\text{ A}$
 $t_{don} = 0,13\ \mu\text{s}$
 $t_{Eon} = 0,39\ \mu\text{s}$
Figure 3. Turn-off Switching Waveforms & definition of t_f
 Output inverter IGBT

 $U_c(100\%) = 600\text{ V}$
 $I_c(100\%) = 25\text{ A}$
 $t_f = 0,092\ \mu\text{s}$
Figure 4. Turn-on Switching Waveforms & definition of t_r
 Output inverter IGBT

 $U_c(100\%) = 600\text{ V}$
 $I_c(100\%) = 25\text{ A}$
 $t_r = 0,015\ \mu\text{s}$

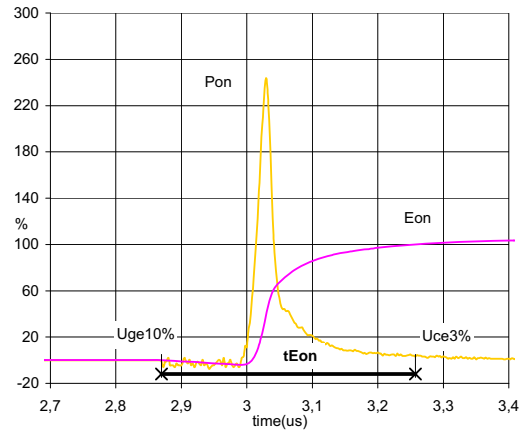
Switching definitions

Figure 5. Turn-off Switching Waveforms & definition of t_{Eoff}
Output inverter IGBT



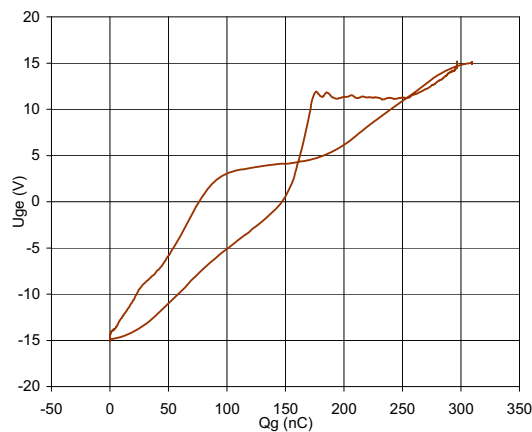
Poff(100%)= 14,96 kW
Eoff(100%)= 1,76 mJ
 t_{Eoff} = 0,40 us

Figure 6. Turn-on Switching Waveforms & definition of t_{Eon}
Output inverter IGBT



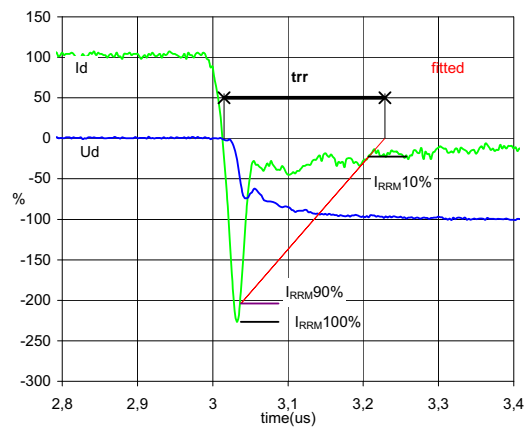
Pon(100%)= 15 kW
Eon(100%)= 1,35 mJ
 t_{Eon} = 0,39 us

Figure 7. Gate voltage vs Gate charge
Output inverter IGBT



Ugeoff= -15 V
Ugeon= 15 V
Uc(100%)= 600 V
Ic(100%)= 25 A
Qg= 309,3 nC

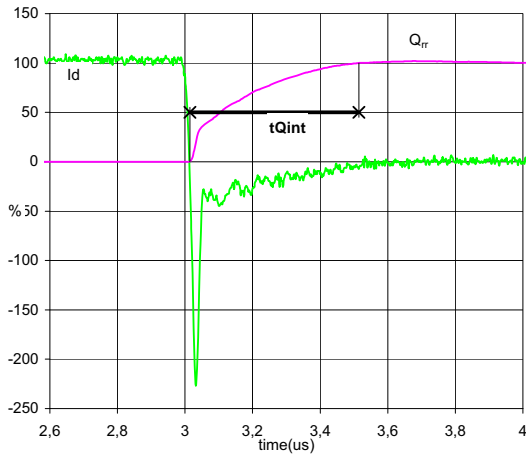
Figure 8. Turn-off Switching Waveforms & definition of t_{rr}
Output inverter FRED



Ud(100%)= 600 V
Id(100%)= 25 A
 I_{RRM} (100%)= 55 A
 t_{rr} = 0,15 us

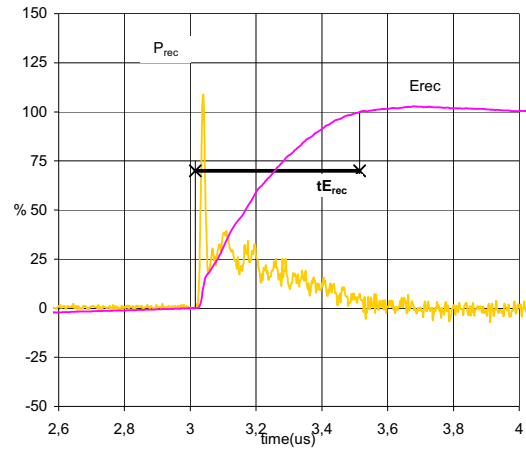
Switching definitions

Figure 9. Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})
Output inverter FRED



Id(100%)= 25 A
Qrr(100%)= 3,419 uC
tQint= 0,50 us

Figure 10. Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})
Output inverter FRED



Prec(100%)= 15 kW
Erec(100%)= 1,55 mJ
tErec= 0,50 us